



Advance Product Change Notification

202608012A : NXP Semiconductors Chandler Fab Product Transfers to NXP ICN8 Wafer Fabrication Site

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 09, 2026

Dear Emma Tempest,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☒ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Location	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

Notification Overview

Description

NXP Semiconductors announced a definitive agreement with Nokia for the sale of our site in Chandler, Arizona, including Chandler Fab, in a phased approach over the next few years.

As a result of this decision, NXP is issuing Advance PCN 202608012A for the Chandler Fab products which have been identified to transfer from NXP CHD Fab (Chandler, Arizona, USA) to NXP ICN8 Fab (Nijmegen, Netherlands).

No change to orderable part number is anticipated upon transfer to ICN8.

Upon qualification completion at ICN8, NXP will issue a Final PCN to relay qualification results. Final PCN will include completed ZVEI Delta Qualification Matrix. No change to the product specification / electrical performance is anticipated.

Please consult with your NXP Global Key Account Manager (GKAM) and your Customer Supply Business Specialist (CSB) for any questions during this transition period.

Reason

NXP Semiconductors announced a definitive agreement with Nokia for the sale of our site in Chandler, Arizona – including Chandler Fab. As a result of this decision, NXP Semiconductors issues Advance PCN 202608012A for the Chandler Fab products which have been identified to transfer from NXP CHD Fab (Chandler, Arizona, USA) to NXP ICN8 Fab (Nijmegen, Netherlands).

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Sample availability will vary by product.

Please work with your NXP Representative for sample availability.

Production

Planned first shipment Feb 29, 2028

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:[view online](#)

Timing and Logistics

The Self Qualification Report will be ready on Sep 30, 2027.

The Final PCN is planned to be issued on: Sep 30, 2027.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 08, 2026.

Limited Qualification Results will be available beginning 30-Sep-2027.

All qualification activity is compliant to AEC-Q100 and ZVEI requirements.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

About NXP Semiconductors

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pioneering people to develop system solutions that make the connected world better, safer, and more secure. Find out more at www.nxp.com.

NXP Semiconductors

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